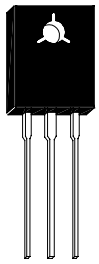
HT882

NPN EPITAXIAL PLANAR TRANSISTOR



TO-126

Description

The HT882 is designed for using in output stage of 1w audio amplifier, voltage regulator, DC-DC converter and relay driver.

Absolute Maximum Ratings (T_A=25°C)

- Maximum Temperatures
  - Storage Temperature ..... -55 ~ +150 °C
  - Junction Temperature ..... +150 °C Maximum
- Maximum Power Dissipation
  - Total Power Dissipation (T_A=25°C) ..... 1 W
  - Total Power Dissipation (T_C=25°C) ..... 10 W
- Maximum Voltages and Currents
  - BV_{CBO} Collector to Base Voltage ..... 40 V
  - BV_{CEO} Collector to Emitter Voltage ..... 30 V
  - BV_{EBO} Emitter to Base Voltage ..... 5 V
  - I_C Collector Current (DC) ..... 3 A
  - I_C Collector Current (Pulse) ..... 7 A
  - I_B Base Current (DC) ..... 0.6 A

Electrical Characteristics (T_A=25°C)

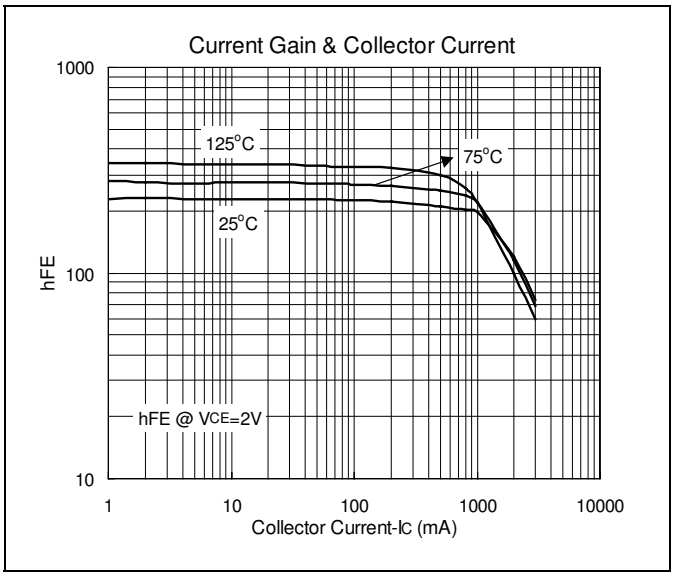
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BV_{CBO}	40	-	-	V	I_C=100uA
BV_{CEO}	30	-	-	V	I_C=1mA
BV_{EBO}	5	-	-	V	I_E=10uA
I_{CBO}	-	-	1	uA	V_{CB}=30V
I_{EBO}	-	-	1	uA	V_{EB}=3V
*$V_{CE(sat)}$	-	-	0.5	V	I_C=2A, I_B=0.2A
*$V_{BE(sat)}$	-	1	2	V	I_C=2A, I_B=0.2A
*h_{FE1}	30	150	-		I_C=20mA, V_{CE}=2V
*h_{FE2}	100	200	500		I_C=1A, V_{CE}=2V
f_T	-	90	-	MHz	I_C=0.1A, V_{CE}=5V
Cob	-	45	-	pF	V_{CB}=10V, f=1MHz, I_E=0

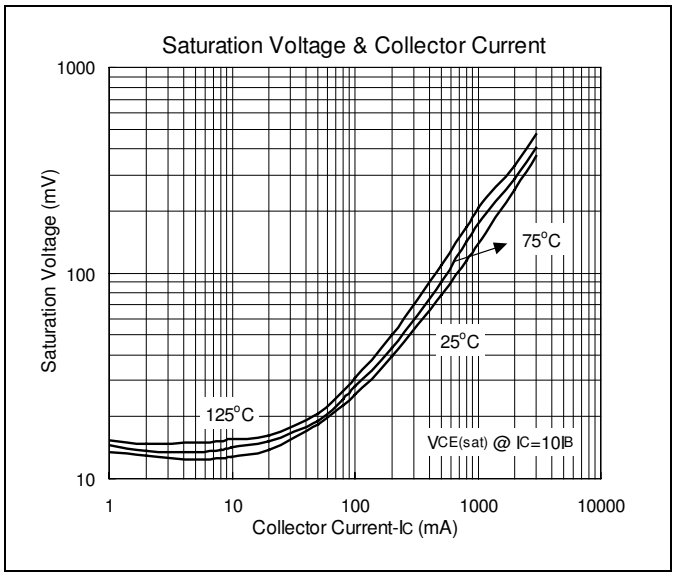
*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%

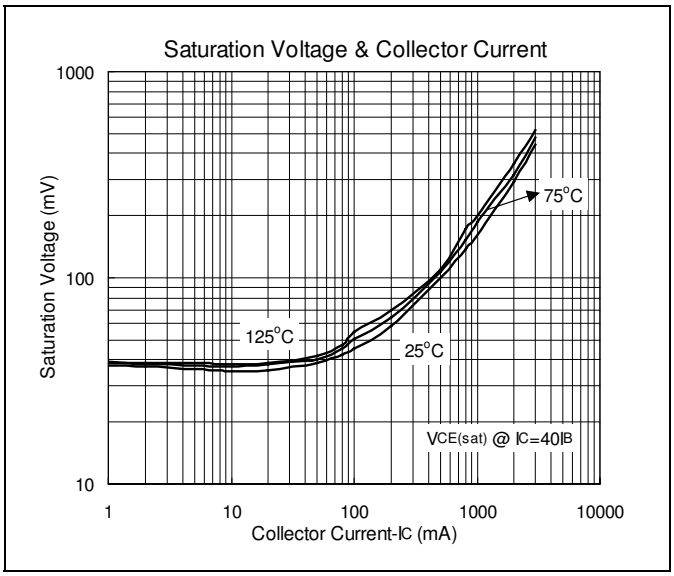
Classification Of hFE2

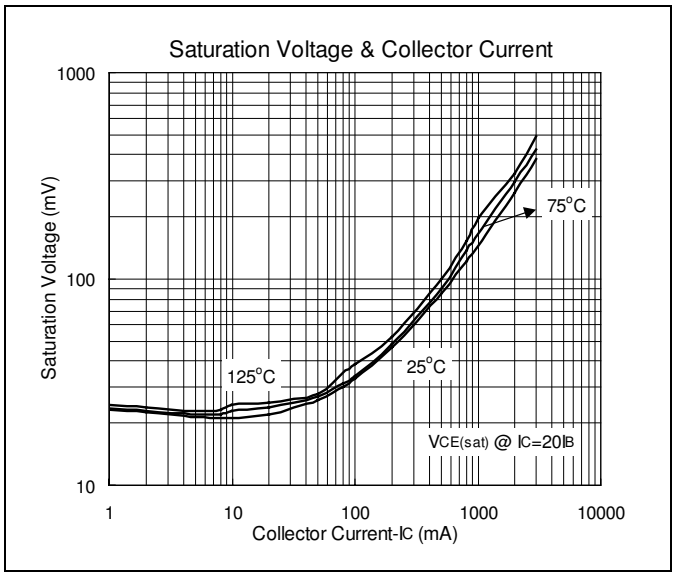
Rank	Q	P	E
Range	100-200	160-320	250-500

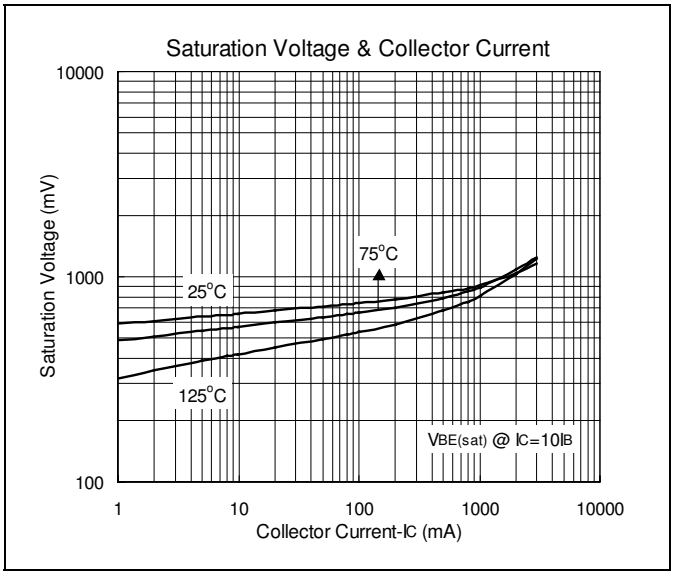
Characteristics Curve

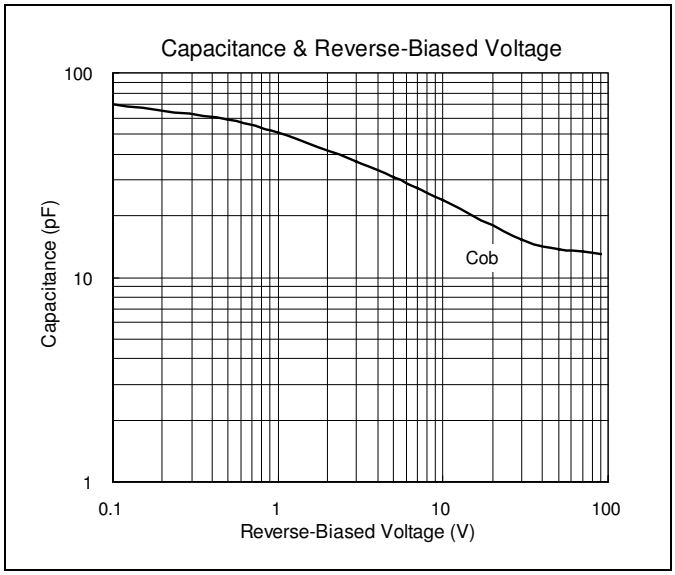


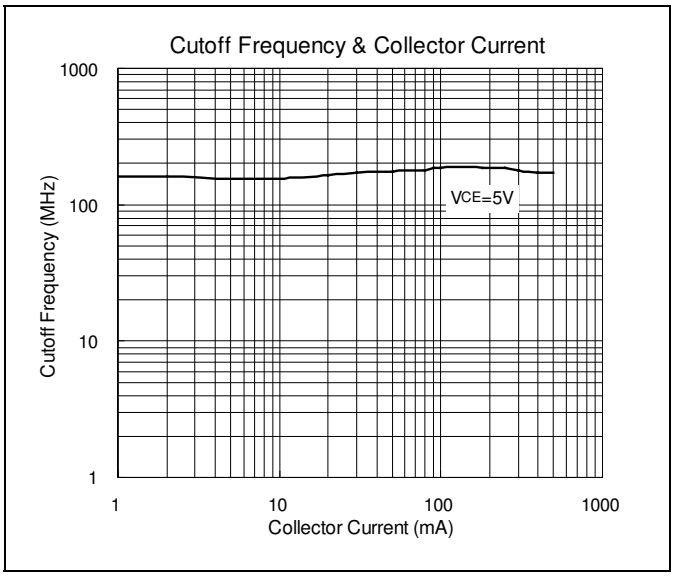


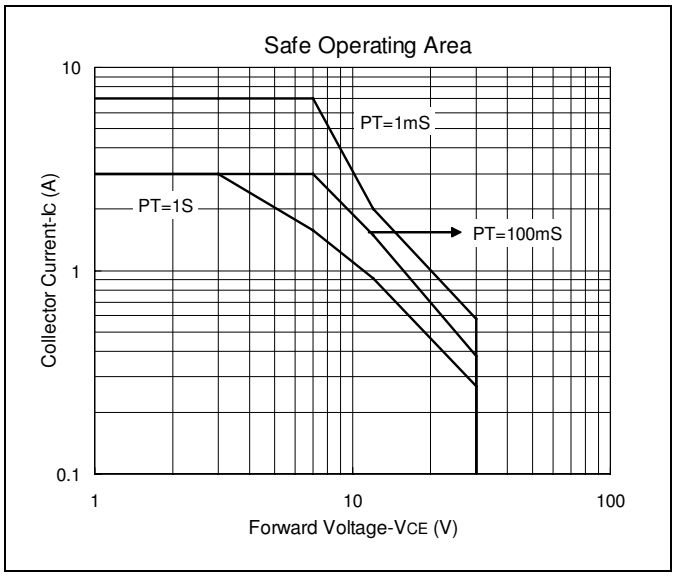




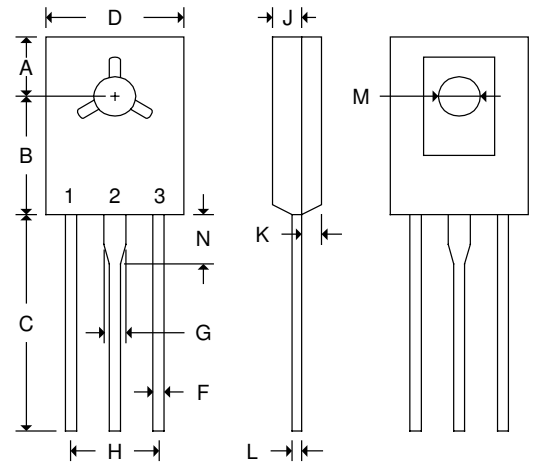





Cutoff Frequency & Collector Current
1000
100
10
1
Cutoff Frequency (MHz)
VCE=5V
1
10
100
1000
Collector Current (mA)

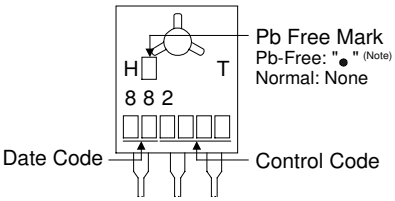

Safe Operating Area
10
1
0.1
Collector Current-Ic (A)
PT=1mS
PT=1S
PT=100mS
1
10
100
Forward Voltage-VCE (V)

TO-126 Dimension



3-Lead TO-126
Plastic Package
HSMC Package Code: T

Marking:



Note: Green label is used for pb-free packing

Pin Style: 1.Emitter 2.Collector 3.Base

Material:
- Lead solder plating: Sn60/Pb40 (Normal), Sn/3.0Ag/0.5Cu or Pure-Tin (Pb-free)
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

DIM	Min.	Max.
A	3.60	4.40
B	6.90	7.60
C	13.00	16.50
D	7.20	8.50
F	0.65	0.88
G	1.00	1.42
H	4.52	4.62
J	1.14	1.50
K	0.90	1.50
L	0.45	0.60
M	2.92	3.40
N	2.00	2.70

Unit: mm

Head Office And Factory:

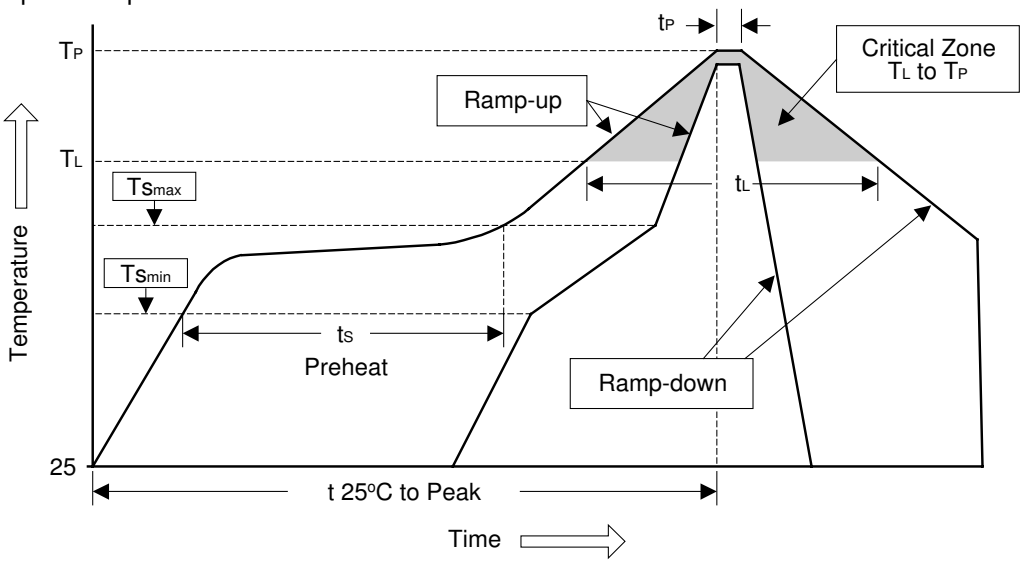
- **Head Office** (Hi-Sincerity Microelectronics Corp.): 10F.,No. 61, Sec. 2, Chung-Shan N. Rd. Taipei Taiwan R.O.C.
  Tel: 886-2-25212056 Fax: 886-2-25632712, 25368454
- **Factory 1:** No. 38, Kuang Fu S. Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
  Tel: 886-3-5983621~5 Fax: 886-3-5982931

Soldering Methods for HSMC's Products

1. Storage environment: Temperature=10°C~35°C Humidity=65%±15%

2. Reflow soldering of surface-mount devices

Figure 1: Temperature profile



Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	<3°C/sec	<3°C/sec
Preheat - Temperature Min (Ts_{min}) - Temperature Max (Ts_{max}) - Time (min to max) (ts)	 100°C 150°C 60~120 sec	 150°C 200°C 60~180 sec
Tsmax to T_L - Ramp-up Rate	 <3°C/sec	 <3°C/sec
Time maintained above: - Temperature (T_L) - Time (t_L)	 183°C 60~150 sec	 217°C 60~150 sec
Peak Temperature (T_P)	240°C +0/-5°C	260°C +0/-5°C
Time within 5°C of actual Peak Temperature (t_P)	10~30 sec	20~40 sec
Ramp-down Rate	<6°C/sec	<6°C/sec
Time 25°C to Peak Temperature	<6 minutes	<8 minutes

3. Flow (wave) soldering (solder dipping)

Products	Peak temperature	Dipping time
Pb devices.	245°C ±5°C	5sec ±1sec
Pb-Free devices.	260°C +0/-5°C	5sec ±1sec